

DICING TAPE

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ABSTRACT OF THE DISCLOSURE

10 Dicing tape comprises a tackifiable adhesive layer
which is composed mainly of a polyimide and has a peel
strength of 0.02 N/mm (20 gf/cm) or greater as the
adhesive strength at near room temperature (20-50°C) and
a cured peel strength of 0.3 N/mm (300 gf/cm) or greater.
The tape exhibits adhesive strength with silicon wafers
sufficiently high to allow dicing at near room
15 temperature, and also exhibits high adhesive strength
with circuit boards after curing, in light of the
processing disadvantages of polyimide-based dicing tape
resulting from its low tacky strength (initial adhesive
strength) at low temperatures of around room temperature,
20 which requires a higher ambient temperature to increase
the adhesive force and thus necessitates supplementary
heating equipment.